



**THE DATASHEET OF  
NTD85N02R-1G**



# NTD85N02R

## Power MOSFET 24 Volts, 85 Amps Single N-Channel, DPAK/IPAK

### Features

- Planar HD3e Process for Fast Switching Performance
- Low  $R_{DS(on)}$  to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Low Gate Charge to Minimize Switching Losses
- Pb-Free Packages are Available

### Applications

- CPU Power Delivery
- DC-DC Converters
- Low Side Switching

### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise stated)

Parameter	Symbol	Value	Unit	
Drain-to-Source Voltage	$V_{DSS}$	24	V	
Gate-to-Source Voltage	$V_{GS}$	$\pm 20$	V	
Continuous Drain Current $R_{\theta JA}$ (Note 1)	$I_D$	$T_A = 25^\circ\text{C}$	17	A
		$T_A = 85^\circ\text{C}$	12	
Power Dissipation $R_{\theta JA}$ (Note 1)	$P_D$	$T_A = 25^\circ\text{C}$	2.4	W
Continuous Drain Current $R_{\theta JC}$ (Note 2)	$I_D$	$T_A = 25^\circ\text{C}$	12	A
		$T_A = 85^\circ\text{C}$	8.8	
Power Dissipation $R_{\theta JC}$ (Note 2)	$P_D$	$T_A = 25^\circ\text{C}$	1.25	W
Continuous Drain Current $R_{\theta JC}$ (Note 1)	$I_D$	$T_C = 25^\circ\text{C}$	85	A
		$T_C = 85^\circ\text{C}$	58	
Power Dissipation $R_{\theta JC}$ (Note 1)	$P_D$	$T_C = 25^\circ\text{C}$	78.1	W
Pulsed Drain Current	$T_A = 25^\circ\text{C}, t_p = 10\mu\text{s}$	$I_{DM}$	192	A
Current Limited by Package	$T_A = 25^\circ\text{C}$	$I_{DmaxPkg}$	45	A
Operating Junction and Storage Temperature	$T_J, T_{STG}$		-55 to +150	$^\circ\text{C}$
Source Current (Body Diode)	$I_S$	78	A	
Drain to Source $dV/dt$	$dV/dt$	6	V/ns	
Single Pulse Drain-to-Source Avalanche Energy $T_J = 25^\circ\text{C}, V_{DD} = 30\text{ V}, V_{GS} = 10\text{ V}, I_L = 13\text{ A}_{pk}, L = 1.0\text{ mH}, R_G = 25\ \Omega$	EAS	85	mJ	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	$T_L$	260	$^\circ\text{C}$	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

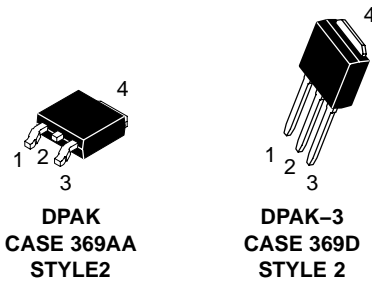
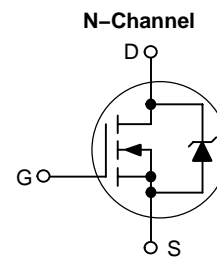
1. Surface-mounted on FR4 board using 1 sq-in pad, 1 oz Cu.
2. Surface-mounted on FR4 board using the minimum recommended pad size.



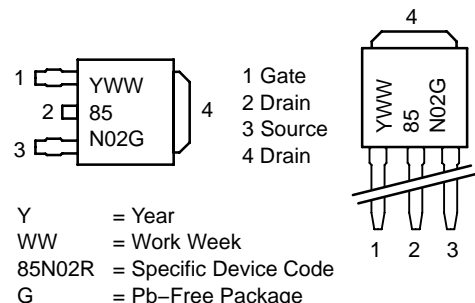
ON Semiconductor®

<http://onsemi.com>

$V_{(BR)DSS}$	$R_{DS(ON) MAX}$	$I_D MAX$
24 V	5.2 m $\Omega$ @ 10 V	85 A



### MARKING DIAGRAM & PIN ASSIGNMENTS



### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

# NTD85N02R

## THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case (Drain)	$R_{\theta JC}$	1.6	°C/W
Junction-to-TAB (Drain)	$R_{\theta JC-TAB}$	3.5	
Junction-to-Ambient – Steady State (Note 1)	$R_{\theta JA}$	52	
Junction-to-Ambient – Steady State (Note 2)	$R_{\theta JA}$	100	

- Surface-mounted on FR4 board using 1 sq-in pad, 1 oz Cu.
- Surface-mounted on FR4 board using the minimum recommended pad size.

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	24	28		V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$			20.5		mV/°C
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}, V_{DS} = 24\text{ V}$	$T_J = 25^\circ\text{C}$		1.5	$\mu\text{A}$
			$T_J = 125^\circ\text{C}$		10	
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA

### ON CHARACTERISTICS (Note 3)

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\ \mu\text{A}$	1.0	1.5	2.0	V	
Negative Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$			4		mV/°C	
Drain-to-Source on Resistance	$R_{DS(ON)}$	$V_{GS} = 10\text{ V}$	$I_D = 20\text{ A}$		4.8	5.2	m $\Omega$
		$V_{GS} = 4.5\text{ V}$	$I_D = 20\text{ A}$		6.5		
Forward Transconductance	$g_{FS}$	$V_{DS} = 10\text{ V}, I_D = 15\text{ A}$		38		S	

### CHARGES AND CAPACITANCES

Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}, V_{DS} = 20\text{ V}$		2050		pF
Output Capacitance	$C_{OSS}$			871		
Reverse Transfer Capacitance	$C_{RSS}$			359		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 5.0\text{ V}, V_{DS} = 10\text{ V}; I_D = 10\text{ A}$		17.7		nC
Threshold Gate Charge	$Q_{G(TH)}$			1.6		
Gate-to-Source Charge	$Q_{GS}$			2.6		
Gate-to-Drain Charge	$Q_{GD}$			7.1		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 10\text{ V}, V_{DS} = 10\text{ V}; I_D = 10\text{ A}$		35.1		nC

### SWITCHING CHARACTERISTICS (Note 4)

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = 10\text{ V}, V_{DS} = 10\text{ V}, I_D = 30\text{ A}, R_G = 3.0\ \Omega$		6.3		ns
Rise Time	$t_r$			77		
Turn-Off Delay Time	$t_{d(OFF)}$			25		
Fall Time	$t_f$			12		

- Pulse Test: pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$ .
- Switching characteristics are independent of operating junction temperatures.

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## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit	
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>							
Forward Diode Voltage	$V_{SD}$	$V_{GS} = 0\text{ V},$ $I_S = 30\text{ A}$	$T_J = 25^\circ\text{C}$		0.81	1.0	V
			$T_J = 125^\circ\text{C}$		0.65		
Reverse Recovery Time	$t_{RR}$	$V_{GS} = 0\text{ V},$ $dI_S/dt = 100\text{ A}/\mu\text{s},$ $I_S = 20\text{ A}$		37.5		ns	
Charge Time	$t_a$			16.8			
Discharge Time	$t_b$			20.7			
Reverse Recovery Charge	$Q_{RR}$			27			nC

## PACKAGE PARASITIC VALUES

Source Inductance	$L_S$	$T_A = 25^\circ\text{C}$		2.49		nH
Drain Inductance, DPAK	$L_D$			0.0164		
Drain Inductance, IPAK*	$L_D$			1.88		
Gate Inductance	$L_G$			3.46		
Gate Resistance	$R_G$			1.2		

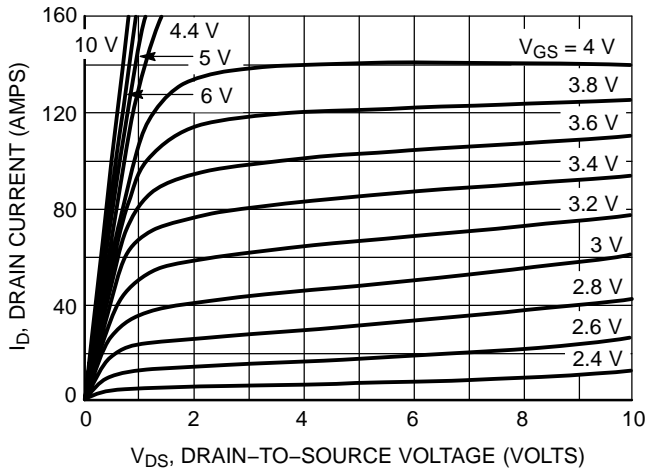
\*Assume standoff of 110 mils.

## ORDERING INFORMATION

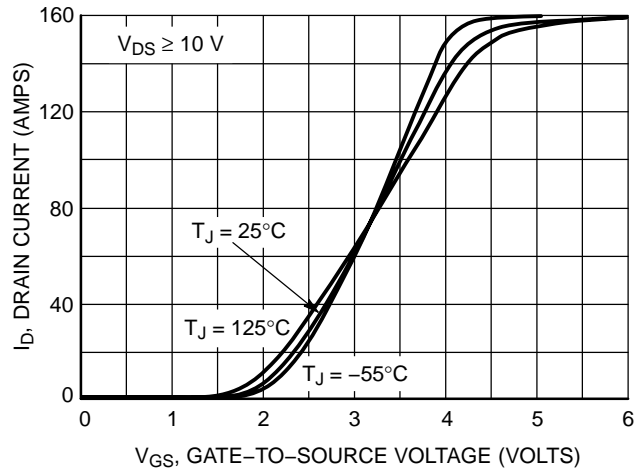
Device	Package	Shipping†
NTD85N02R	DPAK	75 Units / Rail
NTD85N02RG	DPAK (Pb-Free)	
NTD85N02R-001	IPAK	800 / Tape & Reel
NTD85N02R-1G	IPAK (Pb-Free)	
NTD85N02RT4	DPAK	2500 / Tape & Reel
NTD85N02RT4G	DPAK (Pb-Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

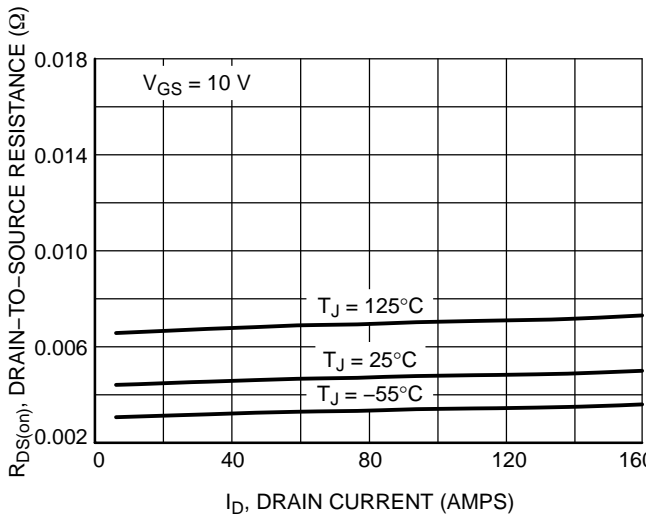
# NTD85N02R



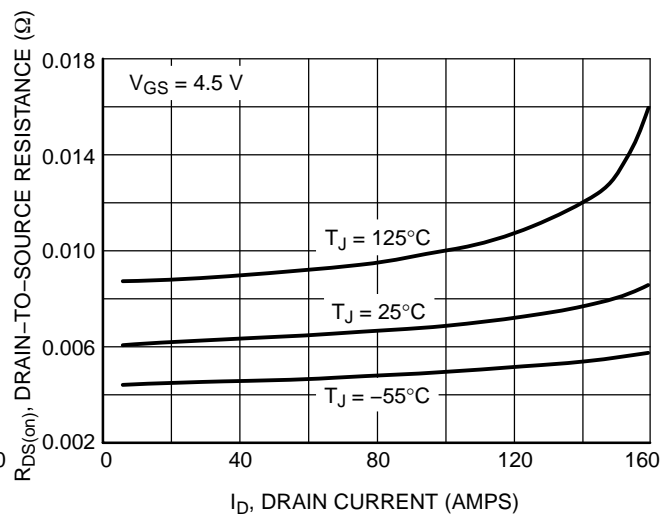
**Figure 1. On-Region Characteristics**



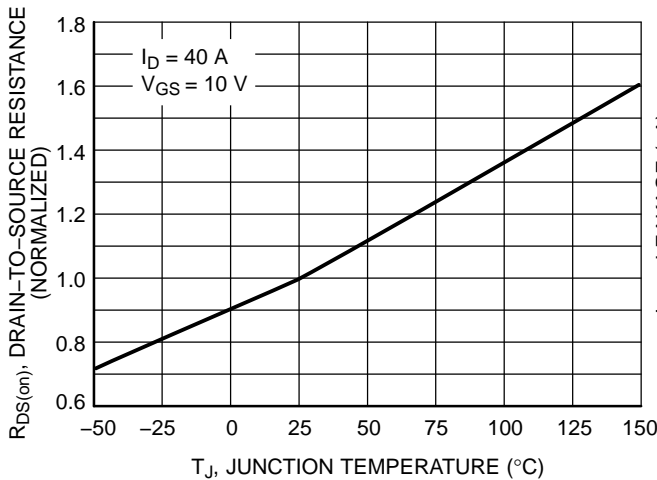
**Figure 2. Transfer Characteristics**



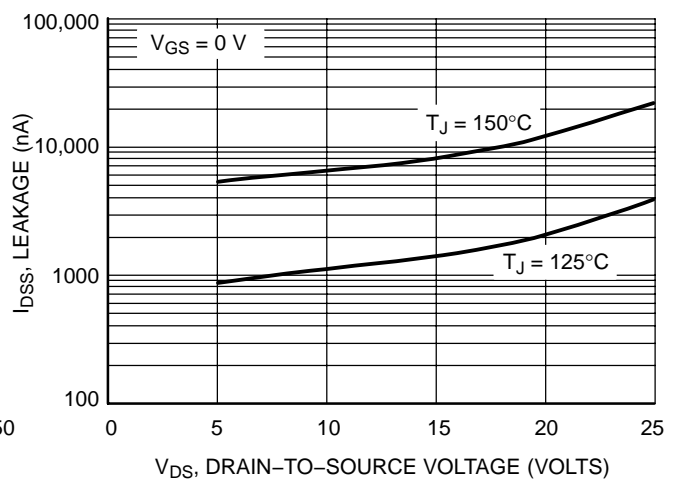
**Figure 3. On-Resistance versus Drain Current and Temperature**



**Figure 4. On-Resistance versus Drain Current and Temperature**



**Figure 5. On-Resistance Variation with Temperature**



**Figure 6. Drain-to-Source Leakage Current versus Voltage**

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## POWER MOSFET SWITCHING

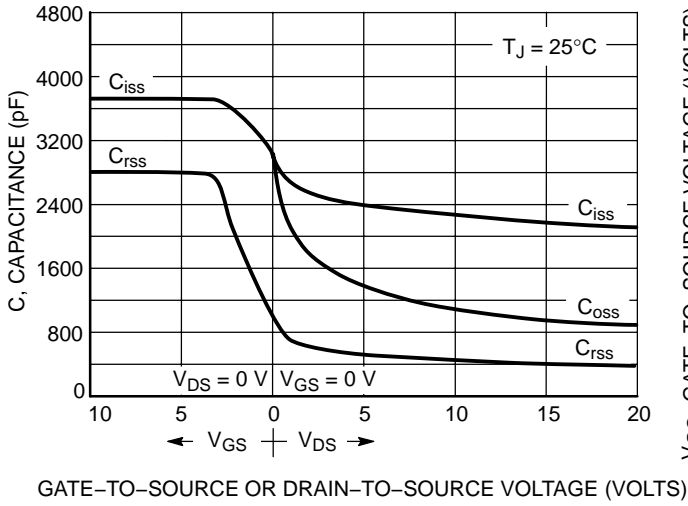


Figure 7. Capacitance Variation

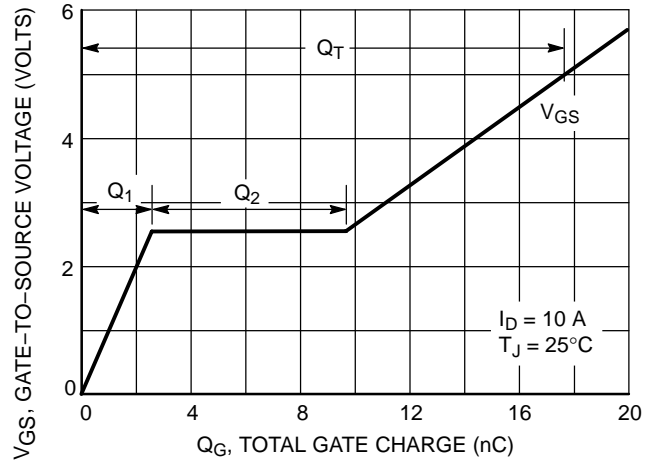


Figure 8. Gate-To-Source and Drain-To-Source Voltage versus Total Charge

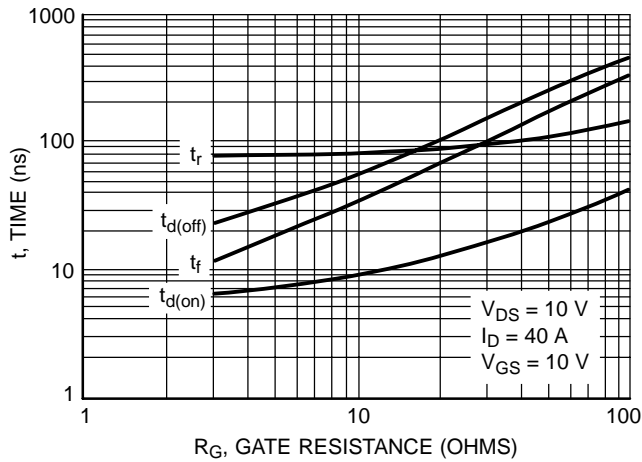


Figure 9. Resistive Switching Time Variation versus Gate Resistance

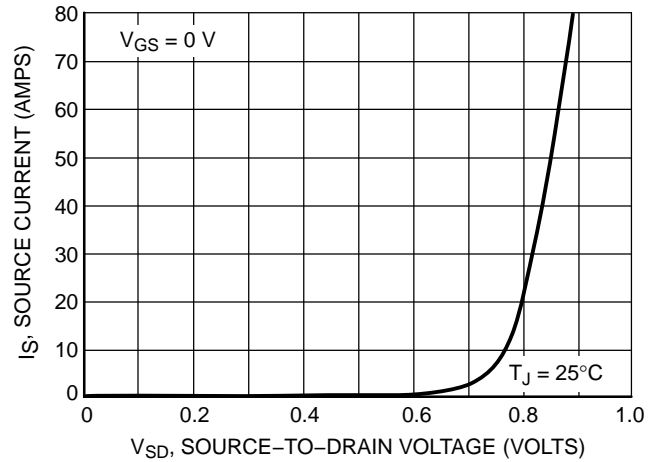


Figure 10. Diode Forward Voltage versus Current

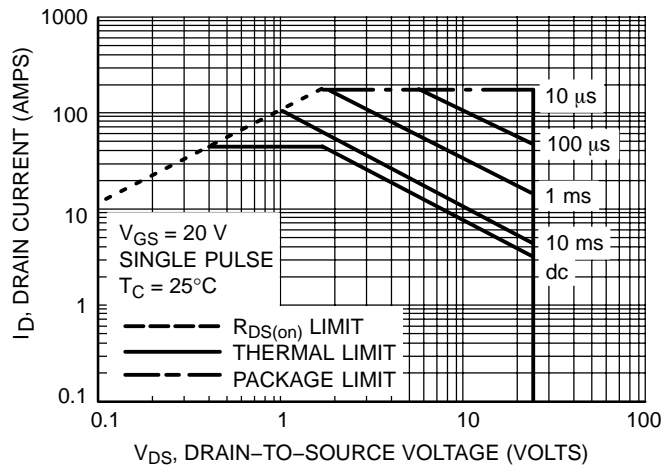


Figure 11. Maximum Rated Forward Biased Safe Operating Area

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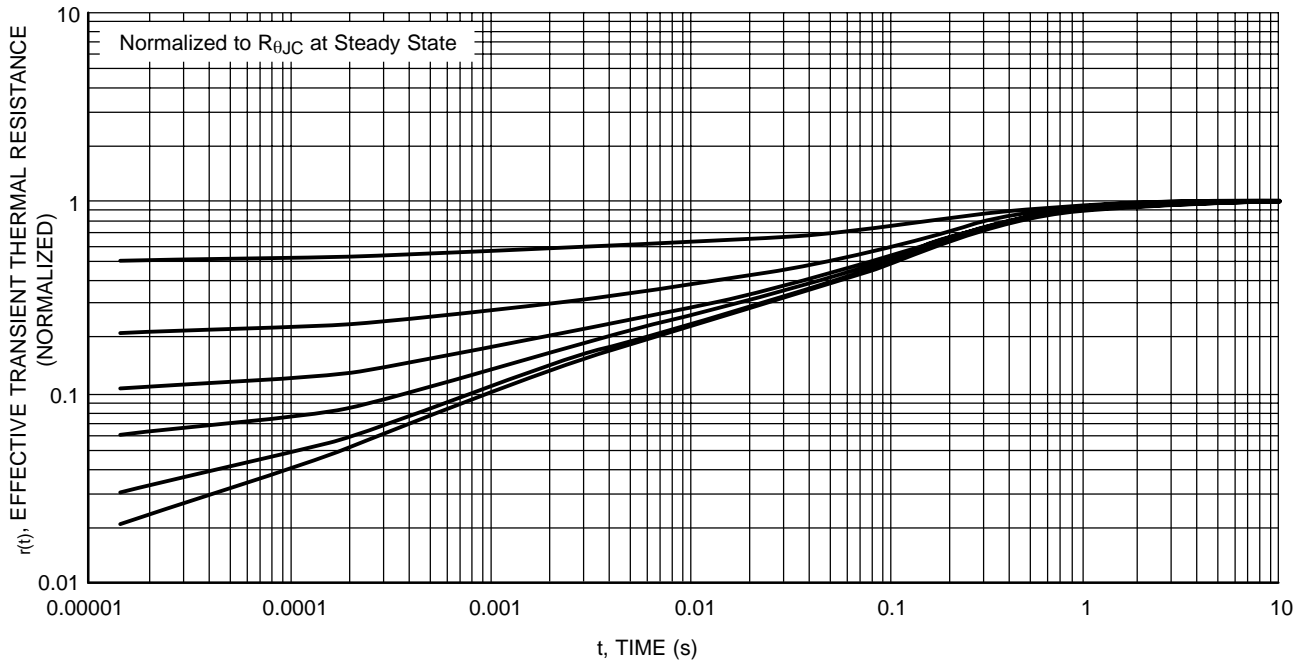


Figure 12. Thermal Response

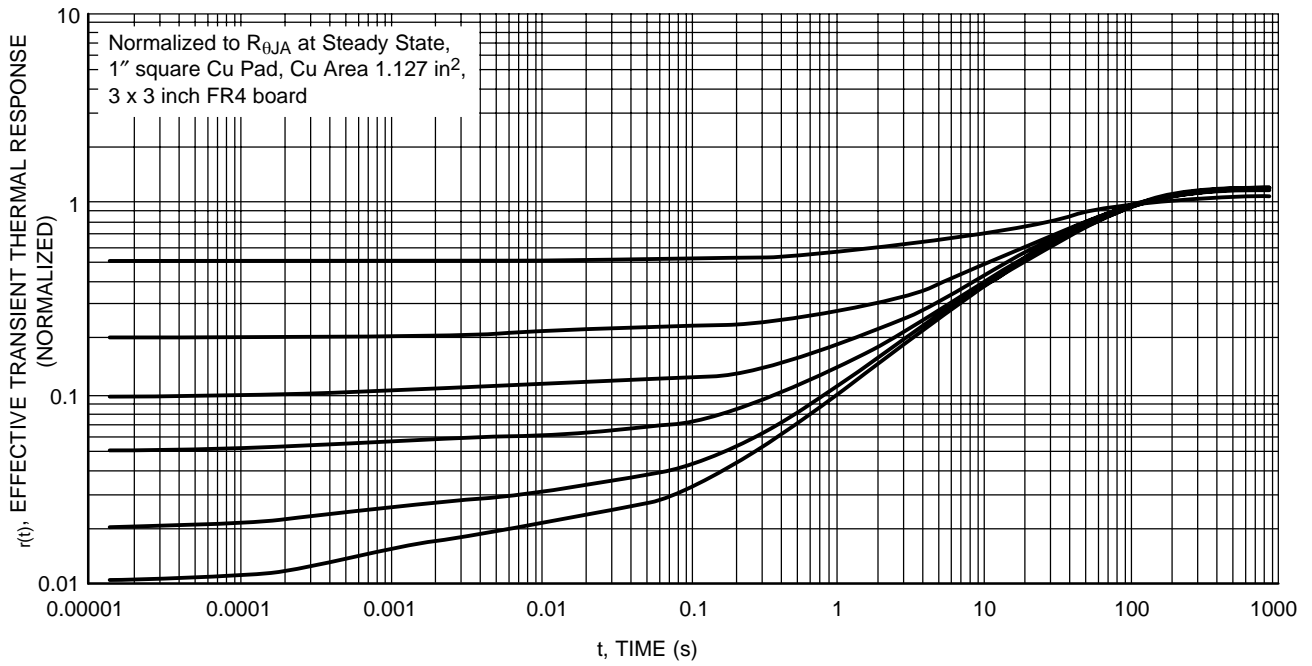
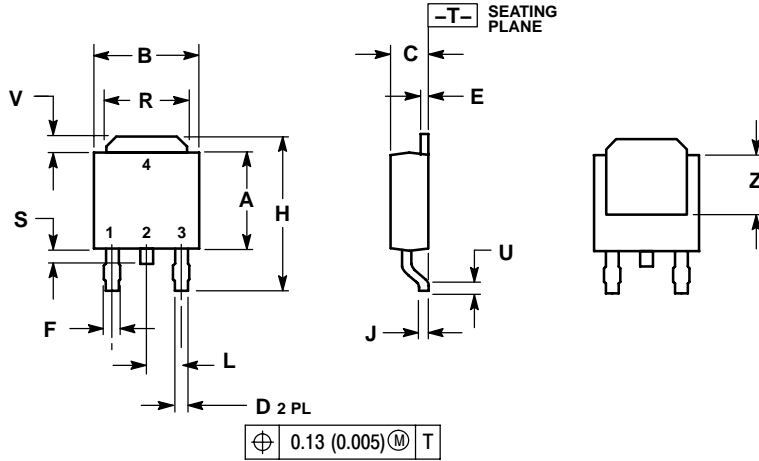


Figure 13. Thermal Response

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## PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)  
CASE 369AA-01  
ISSUE A

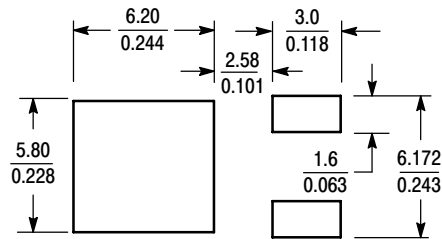


- NOTES:  
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.22
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.025	0.035	0.63	0.89
E	0.018	0.024	0.46	0.61
F	0.030	0.045	0.77	1.14
H	0.386	0.410	9.80	10.40
J	0.018	0.023	0.46	0.58
L	0.090 BSC		2.29 BSC	
R	0.180	0.215	4.57	5.45
S	0.024	0.040	0.60	1.01
U	0.020	---	0.51	---
V	0.035	0.050	0.89	1.27
Z	0.155	---	3.93	---

- STYLE 2:  
PIN 1. GATE  
2. DRAIN  
3. SOURCE  
4. DRAIN

### SOLDERING FOOTPRINT\*



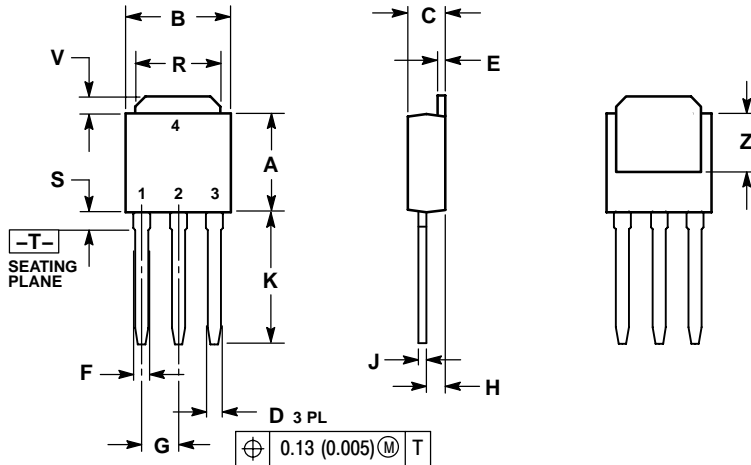
SCALE 3:1  $\left(\frac{\text{mm}}{\text{inches}}\right)$

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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## PACKAGE DIMENSIONS

DPAK-3  
CASE 369D-01  
ISSUE B




NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.35
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.090 BSC		2.29 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.350	0.380	8.89	9.65
R	0.180	0.215	4.45	5.45
S	0.025	0.040	0.63	1.01
V	0.035	0.050	0.89	1.27
Z	0.155	---	3.93	---

STYLE 2:

- PIN 1. GATE
- DRAIN
- SOURCE
- DRAIN

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